



IFW 1765

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q82315

Michel PUECH, et al.

Appln. No.: 10/500,654

Group Art Unit: 1765

Confirmation No.: 2879

Examiner: Mahmoud DAHIMENE

Filed: July 2, 2004

For: A METHOD AND APPARATUS FOR ANISOTROPICALLY ETCHING SILICON
WITH A HIGH ASPECT RATIO

AMENDMENT UNDER 37 C.F.R. § 1.111

MAIL STOP AMENDMENT

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated December 28, 2005, please amend the above-identified application as follows on the accompanying pages.

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